

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/11095	
1.3 Title of PCN	Wafer diameter production conversion to 150 mm for DIACs products housed in DO-35 and MiniMelf packages	
1.4 Product Category	DB3xxx DB4xxx TMMDB3xxx	
1.5 Issue date	2018-09-24	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Franck DUCLOS
2.1.3 Quality Manager	Jean-Paul REBRASSE

**3. Change**

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General	Wafer diameter modification	ST diffusion site in France (Tours)

**4. Description of change**

	<b>Old</b>	<b>New</b>
4.1 Description	5 inches wafers	6 inches wafers
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

**5. Reason / motivation for change**

5.1 Motivation	To pursue standardization of its diffusion production lines, ST has qualified the 6-inch wafer diameter for its DIACs products
5.2 Customer Benefit	YIELD IMPROVEMENT

**6. Marking of parts / traceability of change**

6.1 Description	internal codification and QA number
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**7. Timing / schedule**

7.1 Date of qualification results	2018-09-20
7.2 Intended start of delivery	2018-12-21
7.3 Qualification sample available?	Upon Request

**8. Qualification / Validation**

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

**9. Attachments (additional documentations)**

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11095 Public product.pdf  
11095 PCN-Diac6 inches.pdf

**10. Affected parts**

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	DB4	

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